

MULTI-LAYERED SEMICONDUCTOR DEVICE AND METHOD FOR  
PRODUCING THE SAME

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ABSTRACT OF THE DISCLOSURE

To minimize a size of a semiconductor device and  
10 reduce a thickness thereof as well as improve the yield  
and lower the production cost in the production of a  
semiconductor package, a multi-layered semiconductor  
device is provided, wherein a film-like semiconductor  
package (10) incorporating therein a semiconductor chip  
15 (12) is disposed in a package accommodation opening (11a)  
of a circuit pattern layer to form a circuit board. A  
plurality of such circuit boards are layered together to  
electrically connect circuit patterns (13) of the circuit  
boards with each other via a low melting point metal (14)  
20 or lead beam bonding (13b).

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